G-Premio BOND TECHNIQUE GUIDE





Prior to use, carefully read the instructions for use.

SELECT ETCHING MODE







Etch for 10-15 sec., rinse for 5 sec. and dry.

BONDING PROCEDURE



Apply G-Premio BOND and wait 10 sec.





Light cure.



Start placing composite.

Light curing time

Dry.

	Light curing unit	Distance from light guide tip	
		<10mm	>10mm
	Halogen / LED (700mW/cm²)	10 sec.	20 sec.
	High power LED (>1200 mW/cm²)	5 sec.	10 sec.

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Rinse and drv.

Apply G-Multi PRIMER on ceramic surfaces. Dry.



Apply G-Premio BOND to all surfaces and wait 10 sec.



Light cure.

HYPERSENSITIVITY TREATMENT



Apply G-Premio BOND. Wait 10 sec.



Dry.



Light cure.



Remove unpolymerized layer.